

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: NO-PA66, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

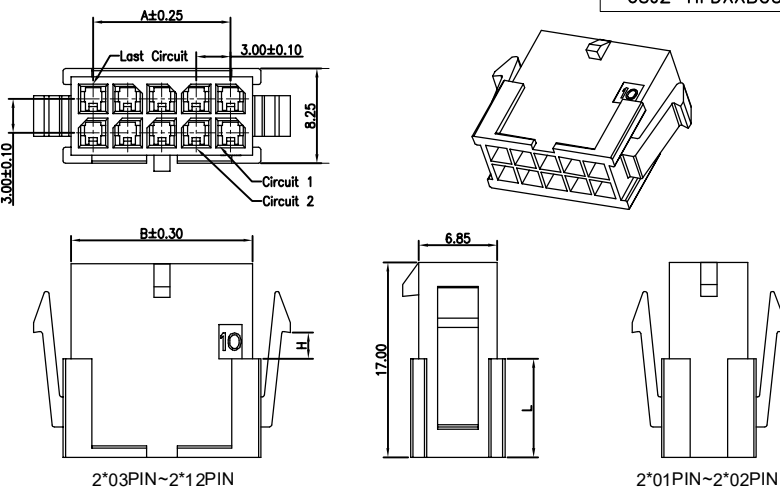
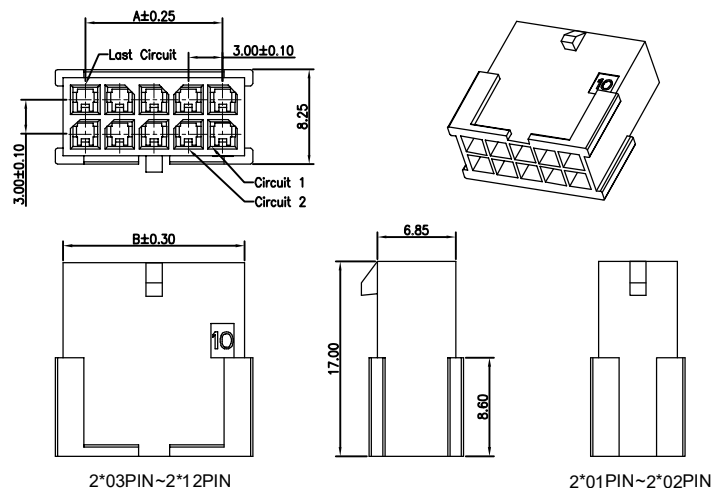
63J2-H F D XX B XX

H=Housing
 F=Female HSG
 D=Double row
 Pin 数码:
 02=2*01PIN
 ~
 24=2*12PIN

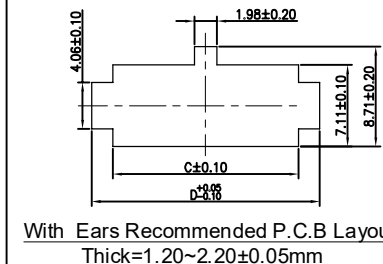
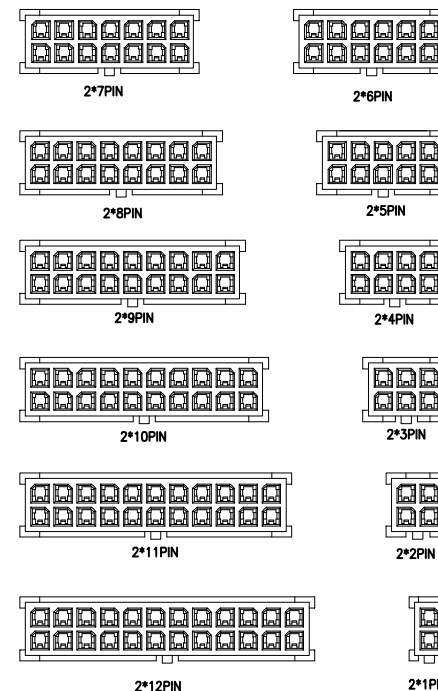
01=WITH OUT EARS
 02=WITH EARS, L=8.60mm, H=2.30mm
 03=WITH EARS, L=9.60mm, H=1.30mm

B=BLACK

Poles	Dimensions(mm)				Poles	Dimensions(mm)			
	A	B	C	D		A	B	C	D
2*01	3.85	4.21	7.89		2*07	18.00	21.85	22.21	25.89
2*02	3.00	6.85	7.21	10.89	2*08	21.00	24.85	25.21	28.89
2*03	6.00	9.85	10.21	13.89	2*09	24.00	27.85	28.21	31.89
2*04	9.00	12.85	13.21	16.89	2*10	27.00	30.85	31.21	34.89
2*05	12.00	15.85	16.21	19.89	2*11	30.00	33.85	34.21	37.89
2*06	15.00	18.85	19.21	22.89	2*12	33.00	36.85	37.21	40.89



63J2-HFDXXB02
 63J2-HFDXXB03



REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION	DRAW	WLY	SCALE	UNIT	mm	SCALE	1:1	PROJ.	SIZE	A4	PART NO.	63J2-HFDXXBXX
AO		NEW			X.X ±0.40	DESIGN	Jensen	2022.08.02						SHEET	1/1	TITLE:	3.00mm CRIMP STYLE CONNE
					X.XX ±0.25	CHECK	Jack	2022.08.02						PROJ.	↺	DRAW NO.	SP-713
					X.XXX ±0.15	APPROVE	Andy	2022.08.02									
					Angle ±3°												
					DIM. TOL												

SOLEPIN 东莞市硕品电子有限公司
 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

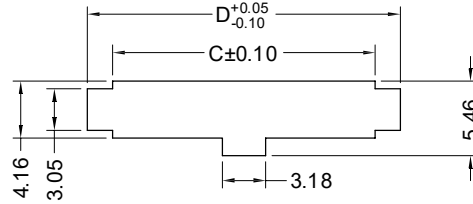
- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 10mW MAX.
- 2.4 INSULATION RESISTANCE: 1000MQ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

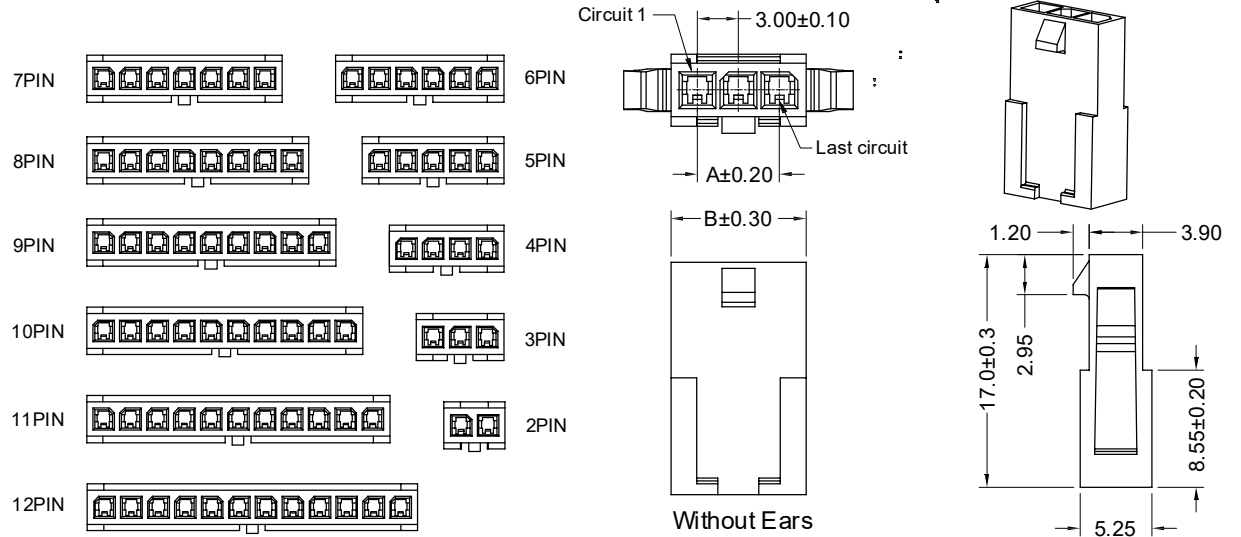
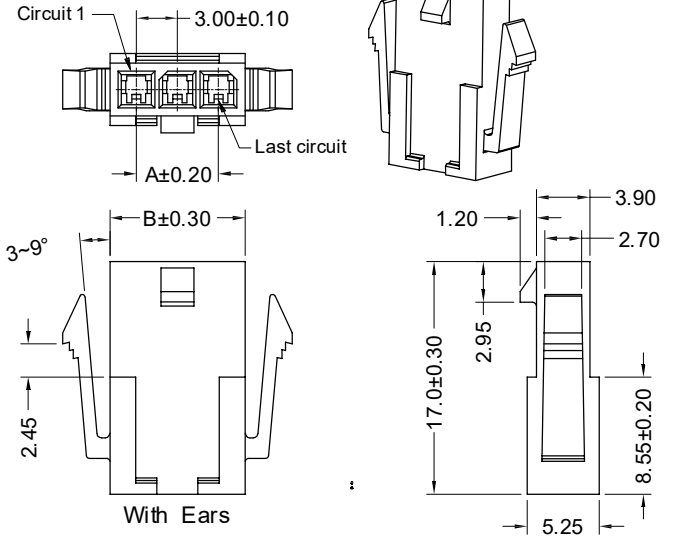
63J2-H F 0 XX B X

- H=Housing
- F=Female HSG
- 0=One row
- Pin 数码: ~
- 12=12PIN
- I=WITHOUT EARS
- G=WITH EARS
- N=Natural
- B=Black

Poles	Dimensions(mm)			
	A	B	C	D
02	3.00	6.90	7.21	10.89
03	6.00	9.90	10.21	13.89
04	9.00	12.90	13.21	16.89
05	12.00	15.90	16.21	19.89
06	15.00	18.90	19.21	22.89
07	18.00	21.90	22.21	25.89
08	21.00	24.90	25.21	28.89
09	24.00	27.90	28.21	31.89
10	27.00	30.90	31.21	34.89
11	30.00	33.90	34.21	37.89
12	33.00	36.90	37.21	40.89



With Ears Recommended P.C.B Layout
Thick=1.60~2.40±0.05mm



OPERATION		DRAW	WLY	2022.08.02
X.X	±0.40	DESIGN	Jensen	2022.08.02
X.XX	±0.25	CHECK	Jack	2022.08.02
X.XXX	±0.15	APPROVE	Andy	2022.08.02
Angle	±3°	UNIT	mm	SCALE 1:1
DIM.	TOL	UNIT	mm	SCALE 1:1

SOLEPIN 东莞市硕品电子有限公司
Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO		NEW		

SIZE	A4	PART NO.	63J2-HFOXXBX
SHEET	1/1	TITLE:	3.00mm Crimp Style Connectors
PROJ.	PROJ.	DRAW NO.	SP-722

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

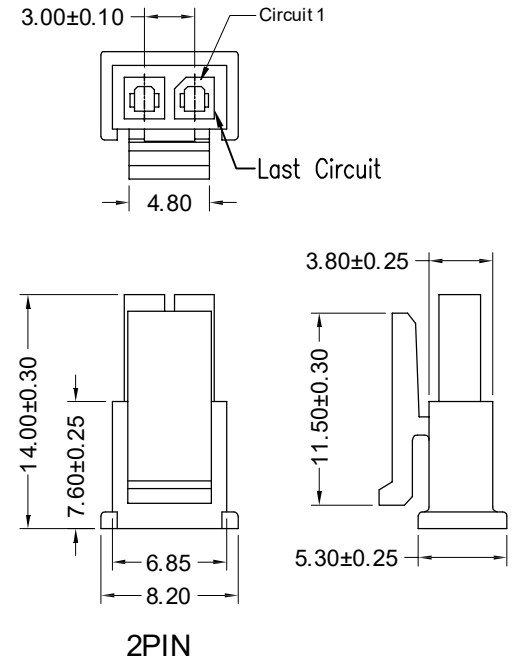
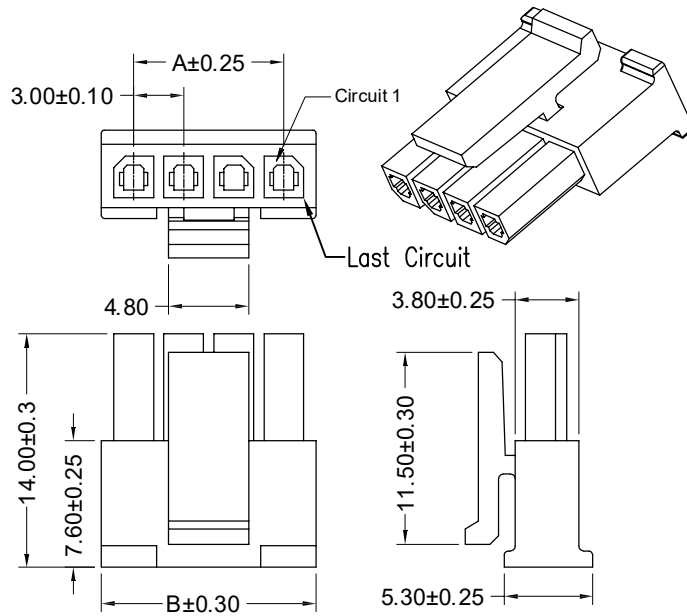
- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 10mW MAX.
- 2.4 INSULATION RESISTANCE: 1000MQ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

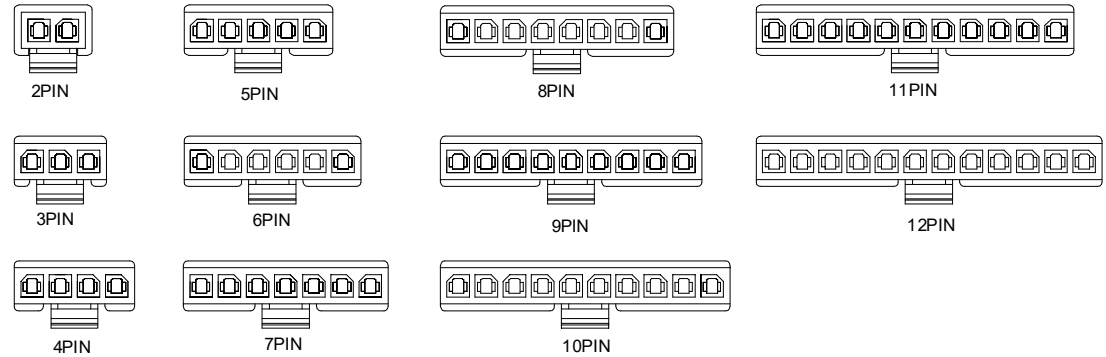
63J2-H M O XX B X

H=Housing
M=Male HSG
O=One row
Pin数码:
02=02PIN
~
12=12PIN

BLANK-ORDINARY
C=GWFI 750°C
B=BLACK
BE=BEIGE



Poles	Dimensions (mm)		Poles	Dimensions (mm)	
	A	B		A	B
03	6.00	9.85	08	21.00	24.85
04	9.00	12.85	09	24.00	27.85
05	12.00	15.85	10	27.00	30.85
06	15.00	18.85	11	30.00	33.85
07	18.00	21.85	12	33.00	36.85



REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION		DRAW		WLY		SOLEPIN 东莞市硕品电子有限公司		
					DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.	SIZE	A4
AO		NEW			X.X	±0.40	DESIGN	Jensen	2022.08.02	Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.XX	±0.25	CHECK	Jack	2022.08.02	SHEET	1/1	TITLE:	3.00mm Crimp Style Connectors
					X.XXX	±0.15	APPROVE	Andy	2022.08.02	PROJ.	↺	DRAW NO.	SP-723

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: NO-PA66, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED
IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA,
50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER
50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

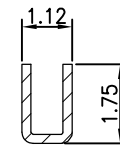
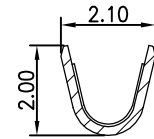
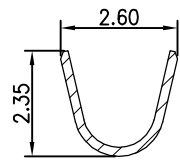
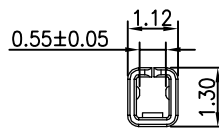
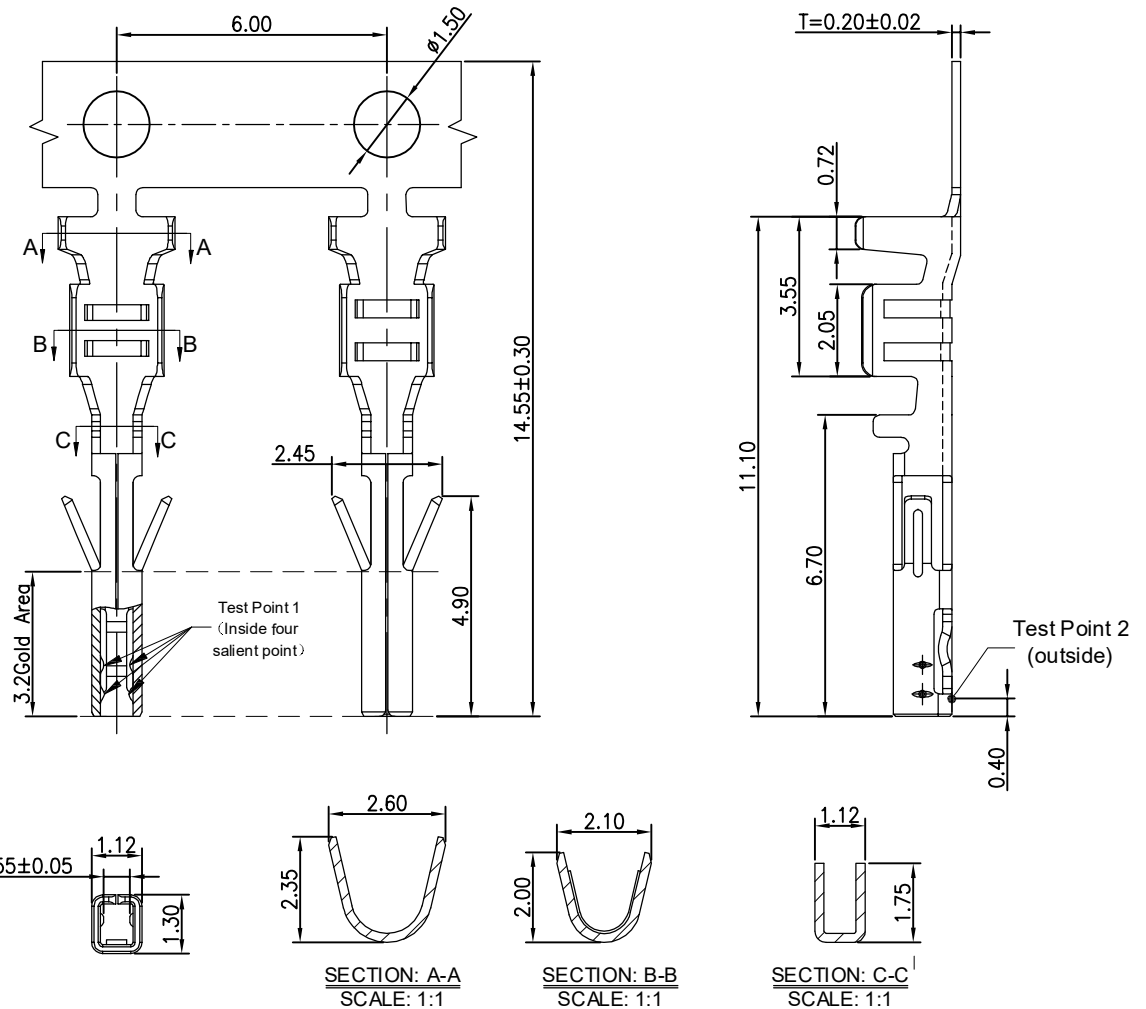
3. ORDER INFORMATION:

63J2-T F P XX V

T=Terminal
F=Female Terminal
P=Phosphor Bronze
V=Convex hull limit

Plating code:

- G6=Contact point gold 30u"(inside test point1)
Gold area 1u"(outside test point2)
Other area Ni30u" min
- G5=Contact point gold 15u"(inside test point1)
Gold area 1u"(outside test point2)
Other area Ni30u" min
- G0=Contact Area Gold Flash(outside test point2)
- SN=Bright tin platin(outside test point 2)



SECTION: A-A
SCALE: 1:1

SECTION: B-B
SCALE: 1:1

SECTION: C-C
SCALE: 1:1

					OPERATION	DRAW	WLY	2022.08.02	SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.					
					X.X ±0.40	DESIGN	Jensen	2022.08.02						
					X.XX ±0.25	CHECK	Jack	2022.08.02						
					X.XXX ±0.15	APPROVE	Andy	2022.08.02						
AO		NEW			Angle ±3°				SIZE	A4	PART NO.	63J3-TFPXXV		
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	SHEET	1/1	TITLE:	WAFER 3.0MM
									PROJ.	SP-714	DRAW NO.			

电镀图

NOTES:

1. FINISH:

- 1.1 HOUSING: NO-PA66, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

63J2-T M P XX

T=Terminal

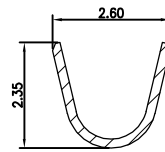
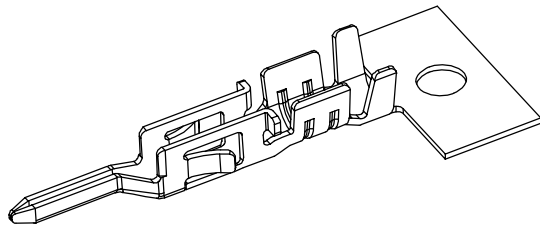
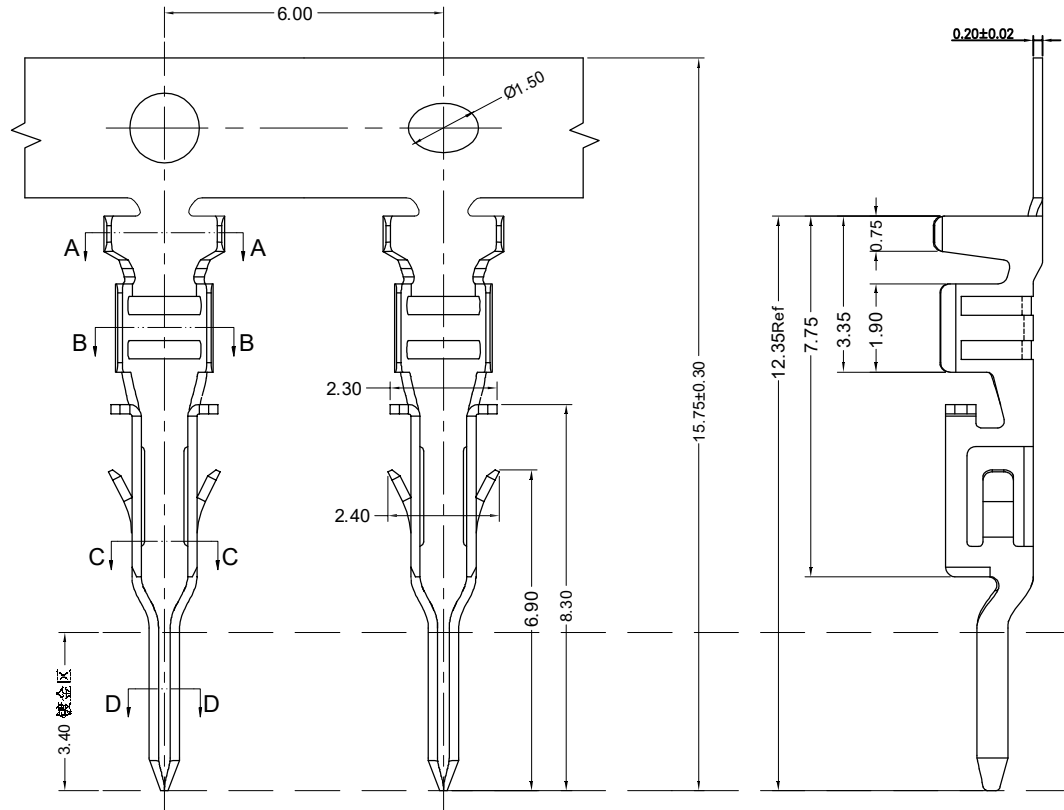
M=Male Terminal

P=Phosphor Bronze

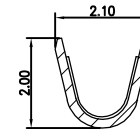
Plating code:

G6=Ni 30u"min; Contact Area 30u" Au

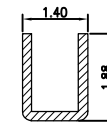
SN=Ni 30u"min; Bright tin 70u" Min



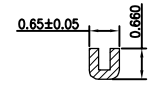
SECTION: A-A
SCALE: 1:1



SECTION: B-B
SCALE: 1:1



SECTION: C-C
SCALE: 1:1



SECTION: D-D
SCALE: 1:1

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.	SIZE	A4	PART NO.	63J2-TMPXX
AO		NEW			Angle	±3°						SHEET	1/1	TITLE:	WAFER 3.0MM
												PROJ.	↻	DRAW NO.	SP-366

SOLEPIN 东莞市硕品电子有限公司
Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: NO-PA66, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

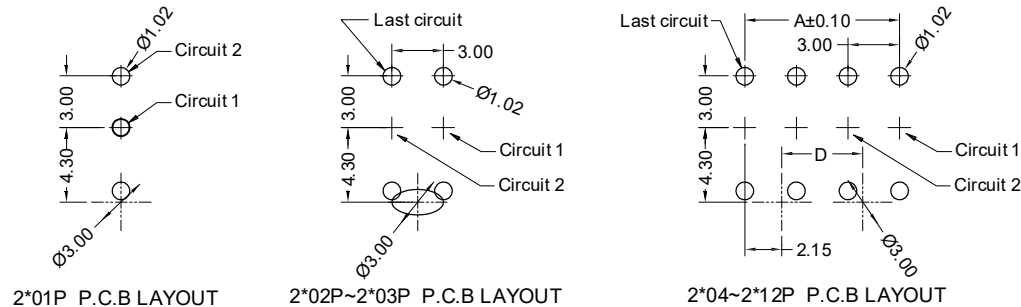
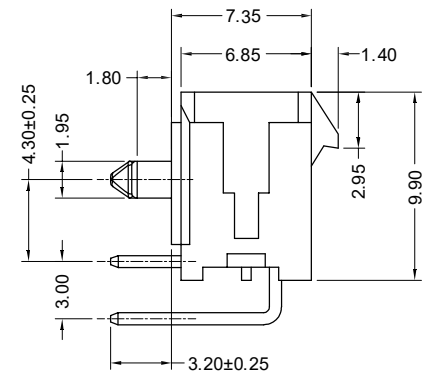
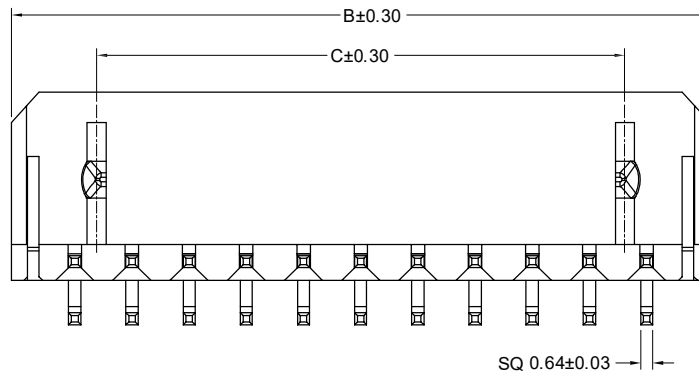
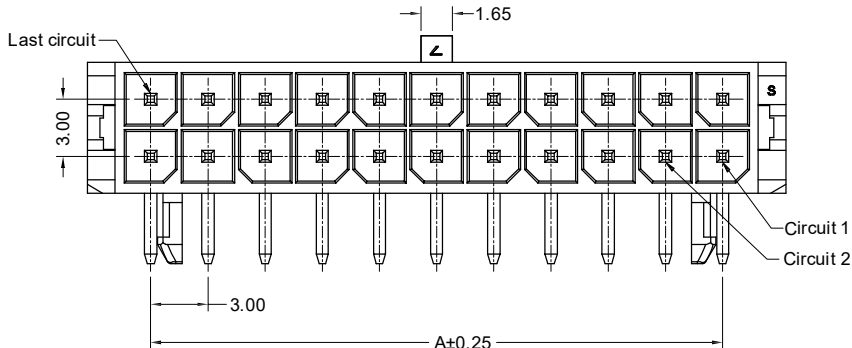
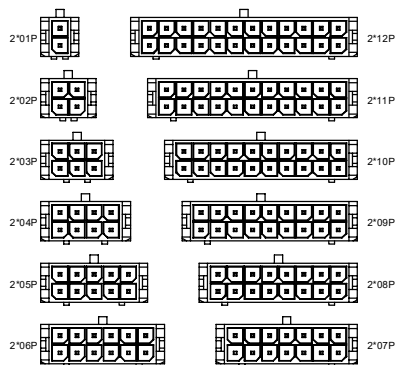
3. ORDER INFORMATION:

63J2-W D R D-XX XX B X A

W=Wafer
 D=Double row
 R=Right Angle 90°
 D=DIP
 A=WITH POSITIONING COLUMN
 T=TRAY
 R=REEL
 B=BLACK

Pin 数码:
 02=2*01PIN
 ~
 24=2*12PIN
 S6=Contact Area Au 30u" Min;
 Solder Area SN 100u" Min;
 Ni50u" Min
 G0=GOLD FLASH
 G3=GOLD 4u"
 SW=MATTE TIN
 SN=BRIGHT TIN

Poles	Dimensions (mm)			
	A	B	C	D
2*01	---	6.65	2.00	---
2*02	3.00	9.65	2.00	---
2*03	6.00	12.65	2.00	---
2*04	9.00	15.65	6.70	4.70
2*05	12.00	18.65	9.70	7.70
2*06	15.00	21.65	12.70	10.70
2*07	18.00	24.65	15.70	13.70
2*08	21.00	27.65	18.70	16.70
2*09	24.00	30.65	21.70	19.70
2*10	27.00	33.65	24.70	22.70
2*11	30.00	36.65	27.70	25.70
2*12	33.00	39.65	30.70	28.70



REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION		DRAW		WLY		2022.08.02		SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.	
					X.X	±0.40	DESIGN	Jensen	2022.08.02					
					X.XX	±0.25	CHECK	Jack	2022.08.02	SIZE	A4	PART NO.	63J2-WDRD-XXXXBXA	
AO		NEW			X.XXX	±0.15	APPROVE	Andy	2022.08.02	SHEET	1/1	TITLE:	WAFER 3.0MM Housing 双排	
					Angle	±3°				PROJ.	☞	DRAW NO.	SP-719	
					DIM.	TOL	UNIT	mm	SCALE	1:1				

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: NO-PA66, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED
IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA,
50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER
50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

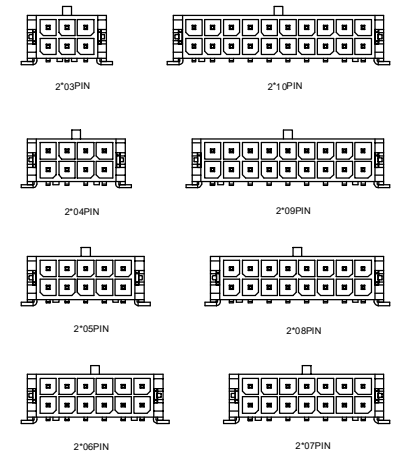
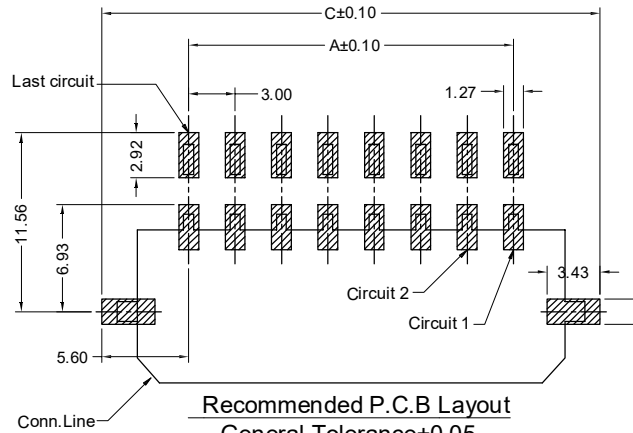
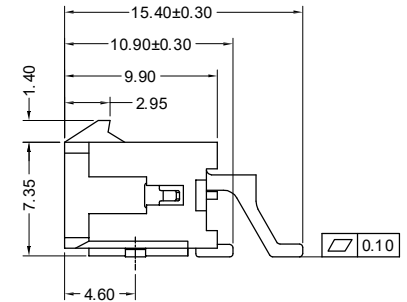
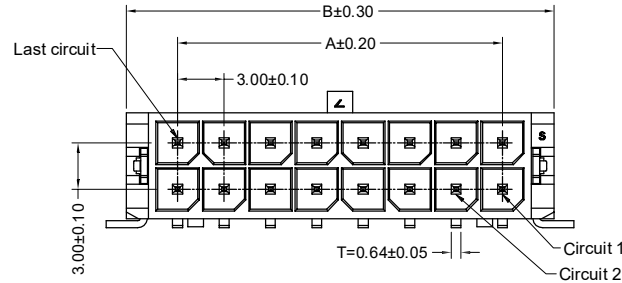
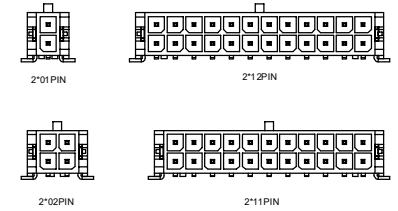
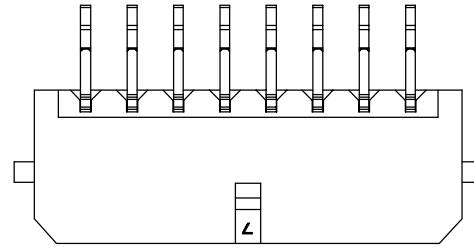
3. ORDER INFORMATION:

63J2-W D R S-XX XX B X D

W=Wafer
D=Double row
R=Right Angle 90°
S=SMT
Pin数码:
02=2*01PIN
~
24=2*12PIN

D=The Solder tab
T=Tray
R=Reel
B=Black
SW=Ni 50u" Min;
Matte Tin 100u" Min
G6=Contact Area Au 30u" Min;
Wolder Area Ni 50u" Min;
Matte Tin 100u" Min
G5=Contact Area Au 15u" Min;
Wolder Area Ni 50u" Min;
Matte Tin 100u" Min

Poles	Dimensions(mm)		
	A	B	C
2*01	6.65	11.20	
2*02	3.00	9.65	14.20
2*03	6.00	12.65	17.20
2*04	9.00	15.65	20.20
2*05	12.00	18.65	23.20
2*06	15.00	21.65	26.20
2*07	18.00	24.65	29.20
2*08	21.00	27.65	32.20
2*09	24.00	30.65	35.20
2*10	27.00	33.65	38.20
2*11	30.00	36.65	41.20
2*12	33.00	39.65	44.20



OPERATION		DRAW	WLY	2022.08.02	SOLEPIN 东莞市硕品电子有限公司			
X.X	±0.40	DESIGN	Jensen	2022.08.02	Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
X.XX	±0.25	CHECK	Jack	2022.08.02	SIZE	A4	PART NO.	63J2-WDRS-XXXXBXD
X.XXX	±0.15	APPROVE	Andy	2022.08.02	SHEET	1/1	TITLE:	WAFER 3.0MM Housing双排
Angle	±3°	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-721
DIM.	TOL							

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO		NEW		

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: NO-PA66, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

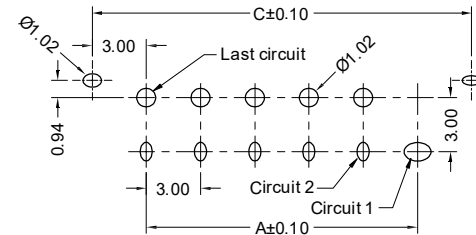
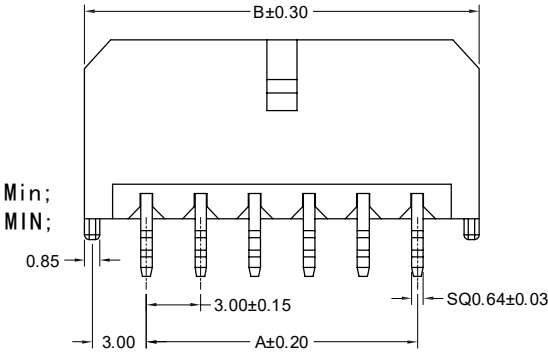
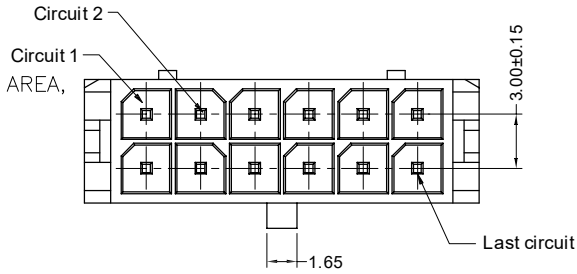
- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

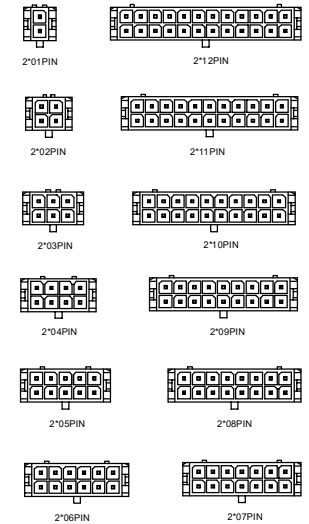
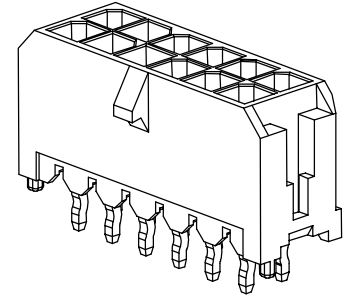
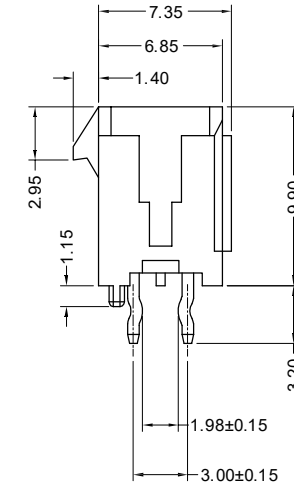
63J2-W D V D-XX XX B X

W=Wafer
 D=Double row
 V=Vertical 180°
 D=DIP
 Pin 数码:
 02=2*01PIN
 ~
 24=2*12PIN

T=TRAY
 R=REEL
 B=BLACK
 S6=Contact Area Au 30u" Min;
 Solder Area SN 100u" MIN;
 Ni 50u" Min
 G0=GOLD FLASH
 G3=GOLD 4u"
 SW=MATTE TIN
 SN=BRIGHT TIN



Recommended P.C.B Layout
 General Tolerance ±0.05



Poles	Dimensions(mm)			Poles	Dimensions(mm)		
	A	B	C		A	B	C
2*01	---	6.85	6.00	2*07	18.00	24.85	24.00
2*02	3.00	9.85	9.00	2*08	21.00	27.85	27.00
2*03	6.00	12.85	12.00	2*09	24.00	30.85	30.00
2*04	9.00	15.85	15.00	2*10	27.00	33.85	33.00
2*05	12.00	18.85	18.00	2*11	30.00	36.85	36.00
2*06	15.00	21.85	21.00	2*12	33.00	39.85	39.00

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION		DRAW	WLY	2022.08.02	
					X.X	±0.40	DESIGN	Jensen	2022.08.02	
					X.XX	±0.25	CHECK	Jack	2022.08.02	
					X.XXX	±0.15	APPROVE	Andy	2022.08.02	
					Angle	±3°	UNIT	mm	SCALE	1:1
					DIM.	TOL			PROJ.	1:1
AO		NEW								

SOLEPIN 东莞市硕品电子有限公司
 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE	A4	PART NO.	63J2-WDVD-XXXXBX
SHEET	1/1	TITLE:	WAFER 3.0MM Housing 双排
PROJ.	☞	DRAW NO.	SP-717

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

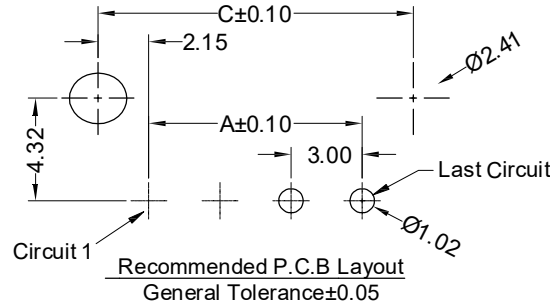
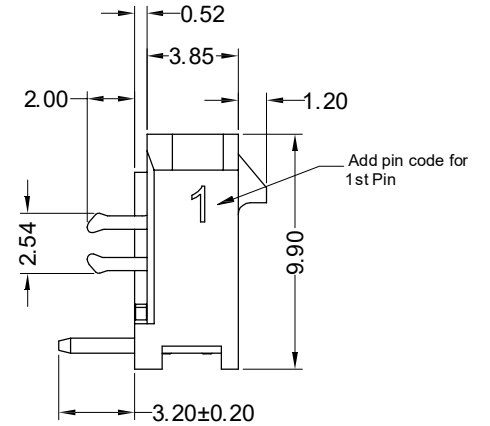
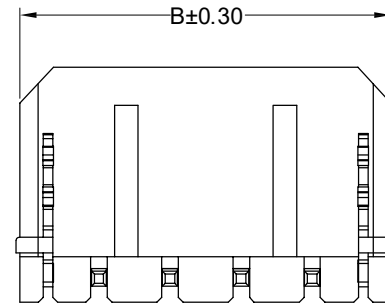
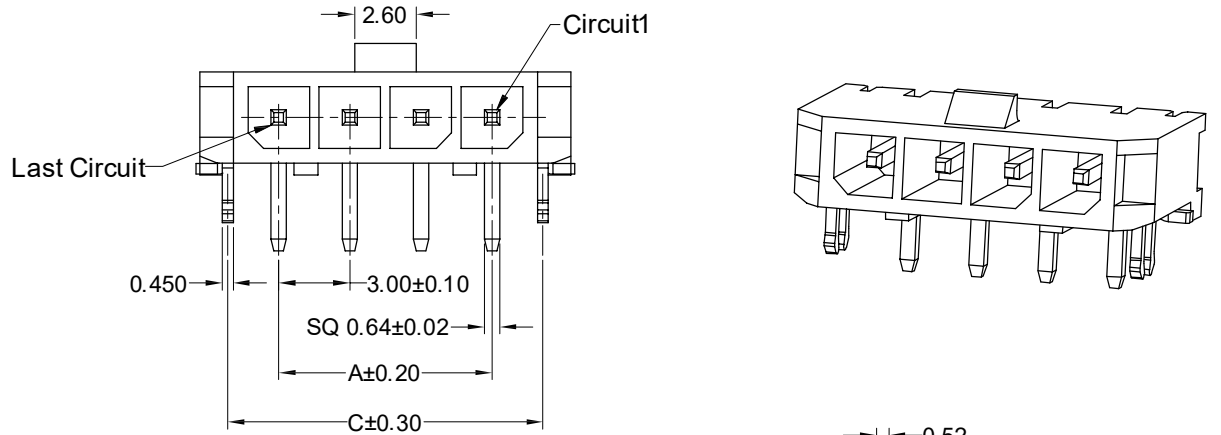
- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 10mW MAX.
- 2.4 INSULATION RESISTANCE: 1000MQ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

63J2-W 0 R D-XX XX B C1

W=Wafer
 O=One row
 R=Right Angle 90°
 D=DIP
 Pin数码:
 02=02PIN
 ~
 12=12PIN

C1=The Harpoon 2.00mm
 B=Black
 SN=Bright Tin



Poles	Dimensions(mm)			Poles	Dimensions(mm)		
	A	B	C		A	B	C
01	---	6.65	4.30	07	18.00	24.65	21.30
02	3.00	9.65	7.30	08	21.00	27.65	24.30
03	6.00	12.65	10.30	09	24.00	30.65	27.30
04	9.00	15.65	13.30	10	27.00	33.65	30.30
05	12.00	18.65	16.30	11	30.00	36.65	33.30
06	15.00	21.65	19.30	12	33.00	39.65	34.30

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION	DRAW	WLY	SCALE	UNIT	mm	SCALE	1:1	PROJ.	SIZE	A4	PART NO.	63J2-WORD-XXXXBC1
					X.X	±0.40	DESIGN	Jensen	2022.08.02								
					X.XX	±0.25	CHECK	Jack	2022.08.02								
					X.XXX	±0.15	APPROVE	Andy	2022.08.02								
					Angle	±3°											
					DIM.	TOL											
AO		NEW												SHEET	1/1	TITLE:	3.00mm Crimp Style Connectors
														PROJ.	☞☜	DRAW NO.	SP-726

SOLEPIN 东莞市硕品电子有限公司
 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE A4 PART NO. 63J2-WORD-XXXXBC1
 SHEET 1/1 TITLE: 3.00mm Crimp Style Connectors
 PROJ. ☞☜ DRAW NO. SP-726

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED
IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA,
50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER
50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

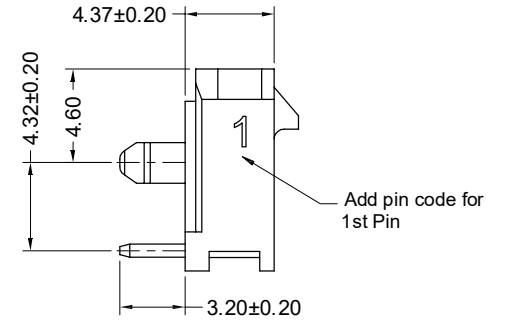
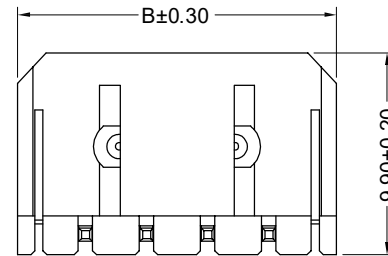
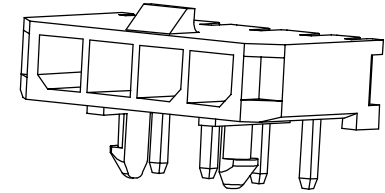
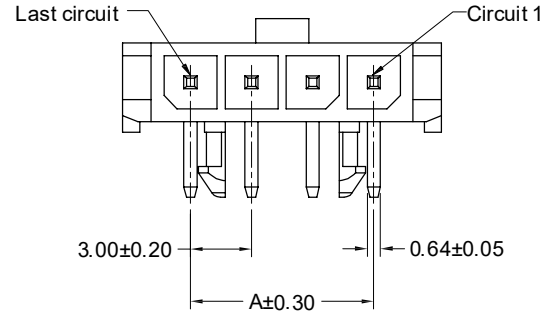
- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 10mW MAX.
- 2.4 INSULATION RESISTANCE: 1000MQ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

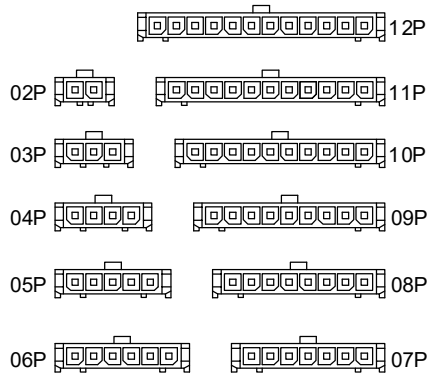
63J2-W 0 R D-XX XX XX B-07

W=Wafer
O=One row
R=Right Angle 90°
D=DIP
Pin 数码:
02=02PIN
~
12=12PIN

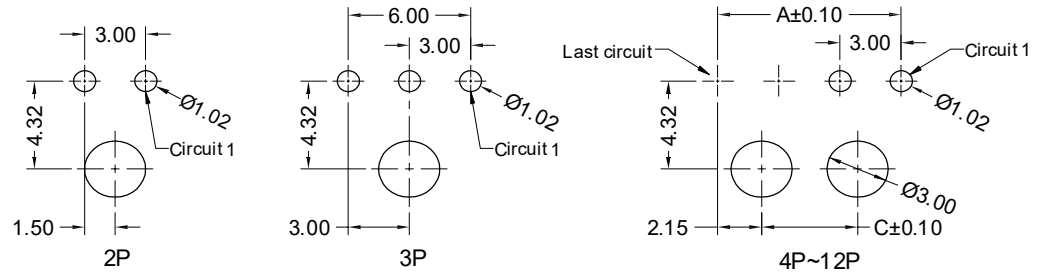
B=BLACK
LP=LCP
66=PA66
SN=Bright Tin
G0=Gold Flash



Poles	Dimensions(mm)		
	A	B	C
02	3.00	9.65	---
03	6.00	12.65	---
04	9.00	15.65	4.70
05	12.00	18.65	7.70
06	15.00	21.65	10.70
07	18.00	24.65	13.70
08	21.00	27.65	16.70
09	24.00	30.65	19.70
10	27.00	33.65	22.70
11	30.00	36.65	25.70
12	33.00	39.65	28.70



CIRCUIT SIZE LAYOUT



Recommended P.C.B Layout

General Tolerance ±0.05

OPERATION		DRAW	WLY	2022.08.02		SOLEPIN 东莞市硕品电子有限公司			
X.X	±0.40	DESIGN	Jensen	2022.08.02		Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
X.XX	±0.25	CHECK	Jack	2022.08.02		SIZE	A4	PART NO.	63J2-WORD-XXXXXXB-07
X.XXX	±0.15	APPROVE	Andy	2022.08.02		SHEET	1/1	TITLE:	3.00mm Crimp Style Connectors
Angle	±3°	UNIT	mm	SCALE	1:1	PROJ.	↺	DRAW NO.	SP-726
DIM.	TOL								

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO		NEW		

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED
IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA,
50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER
50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 10mW MAX.
- 2.4 INSULATION RESISTANCE: 1000MQ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

63J2-W O R S-XX XX B X D

W=Wafer

O=One row

R=Right Angle 90°

S=SMT

Pin No.

02=02PIN

~

24=12PIN

D=The Solder tab

T=Tray

R=Reel

B=Black

SW=Ni 50u" Min;

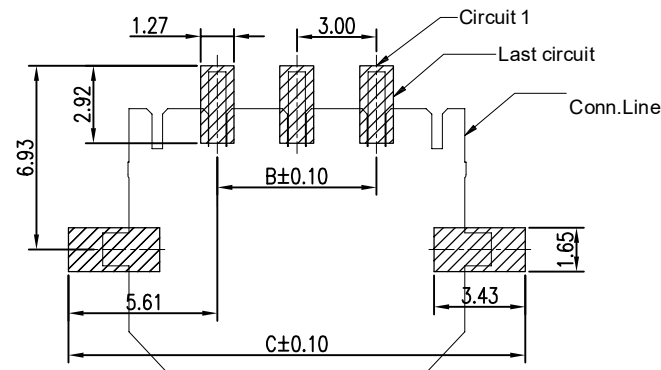
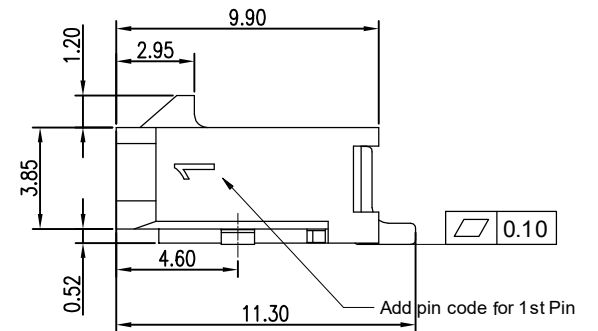
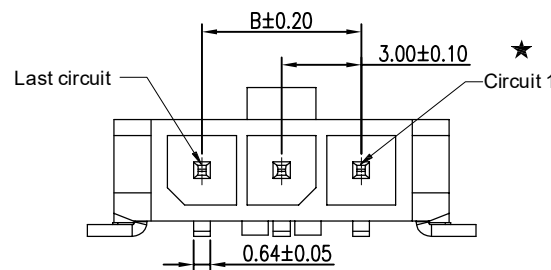
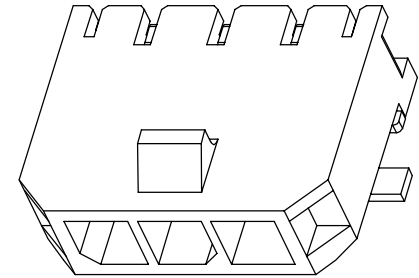
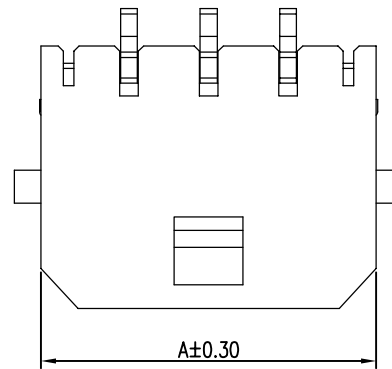
Matte Tin 100u" Min

G5=Contact Area Au 15u" Min;

Solder Area Ni 50u" Min;

Matte Tin 100u" Min

Poles	Dimensions(mm)		
	A	B	C
02	9.65	3.00	14.20
03	12.65	6.00	17.20
04	15.65	9.00	20.20
05	18.65	12.00	23.20
06	21.65	15.00	26.20
07	24.65	18.00	29.20
08	27.65	21.00	32.20
09	30.65	24.00	35.20
10	33.65	27.00	38.20
11	36.65	30.00	41.20
12	39.65	33.00	44.20



RECOMMENDED P.C.B LAYOUT
(TOLERANCE: ±0.05)

					OPERATION	DRAW	WLY	2022.08.02	SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.							
					X.X ±0.40	DESIGN	Jensen	2022.08.02								
					X.XX ±0.25	CHECK	Jack	2022.08.02								
					X.XXX ±0.15	APPROVE	Andy	2022.08.02								
AO			NEW		Angle ±3°				SIZE	A4	PART NO.	63J2-WORS-XXXXBXD				
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	SHEET	1/1	TITLE:	3.00mm Crimp Style Connectors	
									PROJ.	☯	DRAW NO.	SP-728				

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

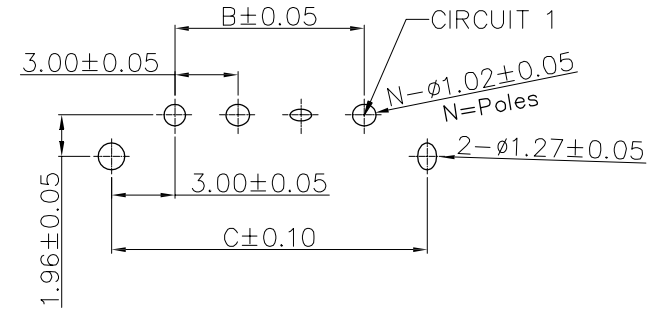
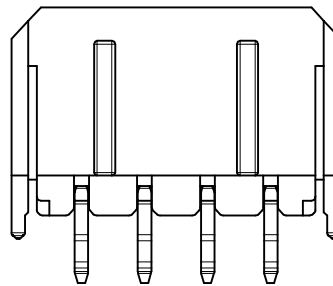
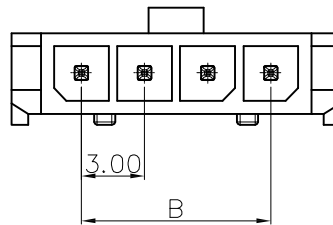
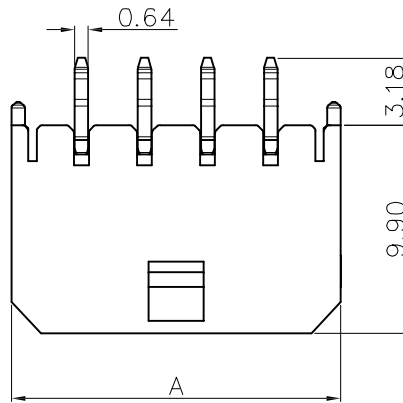
- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 10mW MAX.
- 2.4 INSULATION RESISTANCE: 1000MQ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

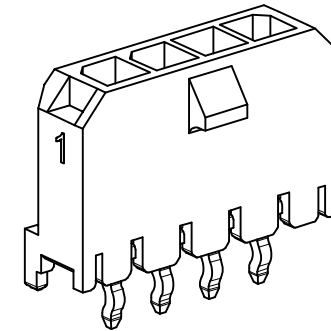
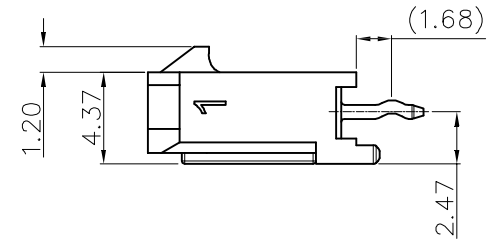
63J2-W O V D-XX SW B I T

- W=Wafer
- O=One row
- V=Vertical 180°
- D=DIP
- Pin 数码:
- 02=02PIN
- ~
- 12=12PIN
- T=Tray
- R=Reel
- I=Stampin terminal
- B=Black
- SW=Matte tin

Poles	Dimensions/mm		
	A	B	C
2	9.65	3.00	9.00
3	12.65	6.00	12.00
4	15.65	9.00	15.00
5	18.65	12.00	18.00
6	21.65	15.00	21.00
7	24.65	18.00	24.00
8	27.65	21.00	27.00
9	30.65	24.00	30.00
10	33.65	27.00	33.00
11	36.65	30.00	36.00
12	39.65	33.00	39.00



Recommended P.C.B Layout(T=1.6mm)



OPERATION		DRAW	WLY	2022.08.02
X.X	±0.40	DESIGN	Jensen	2022.08.02
X.XX	±0.25	CHECK	Jack	2022.08.02
X.XXX	±0.15	APPROVE	Andy	2022.08.02
Angle	±3°	UNIT	mm	SCALE 1:1
DIM.	TOL	UNIT	mm	SCALE 1:1

SOLEPIN 东莞市硕品电子有限公司
Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO		NEW		

SIZE	A4	PART NO.	63J2-WOVD-XXSWBIT
SHEET	1/1	TITLE:	3.00mm Crimp Style Connectors
PROJ.	SP-725	DRAW NO.	

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED
IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA,
50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER
50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 10mW MAX.
- 2.4 INSULATION RESISTANCE: 1000MQ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

63J2-W 0 V D-XX XX XX B-07

W=Wafer
0=One row
V=Vertical 180°
D=DIP

B=BLACK
LP=LCP
66=PA66

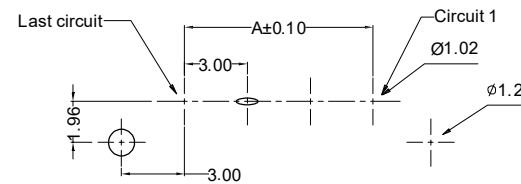
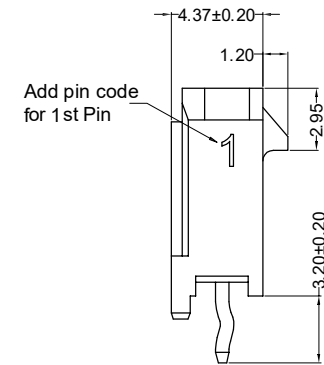
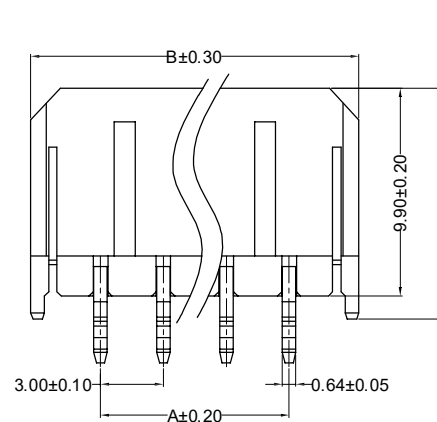
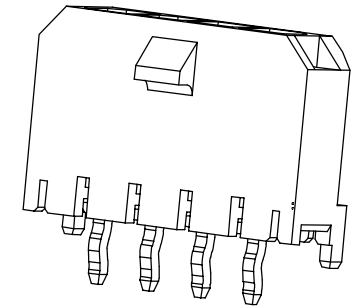
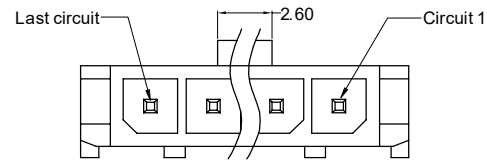
SW=MATTE TIN
SN=BRIGHT TIN

Pin数码:
02=02PIN
~
12=12PIN



CIRCUIT SIZE LAYOUT

Poles	Dimensions (mm)	
	A	B
2	3.00	9.65
3	6.00	12.65
4	9.00	15.65
5	12.00	18.65
6	15.00	21.65
7	18.00	24.65
8	21.00	27.65
9	24.00	30.65
10	27.00	33.65
11	30.00	36.65
12	33.00	39.65



Recommended P.C.B Layout
General Tolerance±0.05

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION		DRAW		WLY		SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					DIM.	TOL	UNIT	mm	SCALE	1:1	SIZE	A4	PART NO.	63J2-WOVD-XXXXB-07
AO		NEW			X.X	±0.40	DESIGN	Jensen	2022.08.02					
					X.XX	±0.25	CHECK	Jack	2022.08.02	SHEET	1/1	TITLE:	3.00mm Crimp Style Connectors	
					X.XXX	±0.15	APPROVE	Andy	2022.08.02	PROJ.	☞	DRAW NO.	SP-724	

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

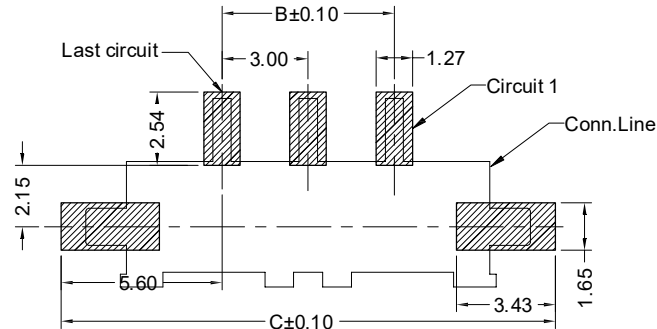
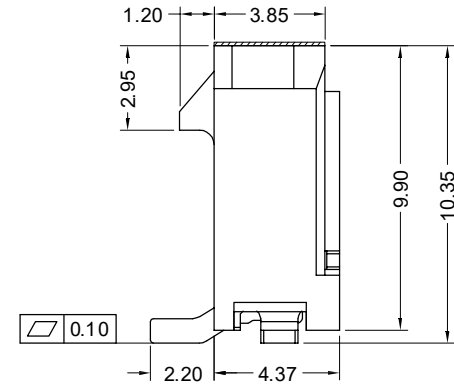
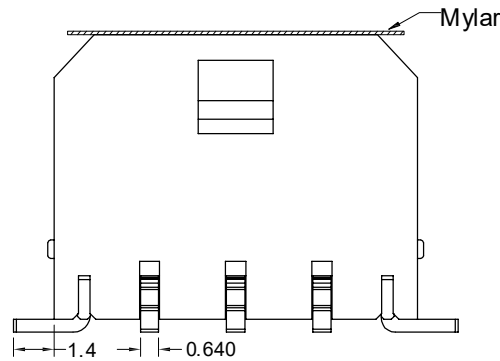
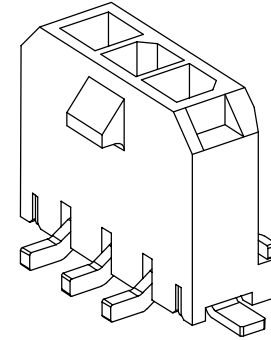
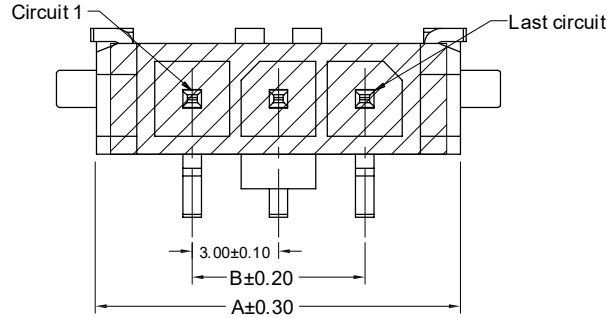
- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 10mW MAX.
- 2.4 INSULATION RESISTANCE: 1000MQ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

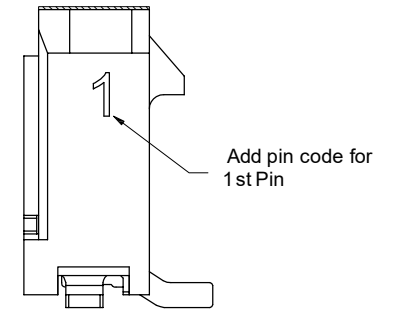
63J2-W O V S-XX XX B R D

- W=Wafer
- O=One row
- V=Vertical 180°
- S=SMT
- Pin No. : 02=02PIN
~
12=12PIN
- D=The Solder tab
- R=Reel
- B=Black
- SW=Matte Tin
- G6=Contact Area Au 30u"Min

Poles	Dimensions(mm)		
	A	B	C
02	9.65	3.00	14.20
03	12.65	6.00	17.20
04	15.65	9.00	20.20
05	18.65	12.00	23.20
06	21.65	15.00	26.20
07	24.65	18.00	29.20
08	27.65	21.00	32.20
09	30.65	24.00	35.20
10	33.65	27.00	38.20
11	36.65	30.00	41.20
12	39.65	33.00	44.20



Recommended P.C.B Layout
General Tolerance±0.05



OPERATION		DRAW	WLY	2022.08.02
X.X	±0.40	DESIGN	Jensen	2022.08.02
X.XX	±0.25	CHECK	Jack	2022.08.02
X.XXX	±0.15	APPROVE	Andy	2022.08.02
Angle	±3°	UNIT	mm	SCALE
DIM.	TOL	UNIT	mm	SCALE

SOLEPIN 东莞市硕品电子有限公司
Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO		NEW		

SIZE	A4	PART NO.	63J2-WOVS-XXXXBRD
SHEET	1/1	TITLE:	3.00mm Crimp Style Connectors
PROJ.	PROJ.	DRAW NO.	SP-727

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: NO-PA66, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

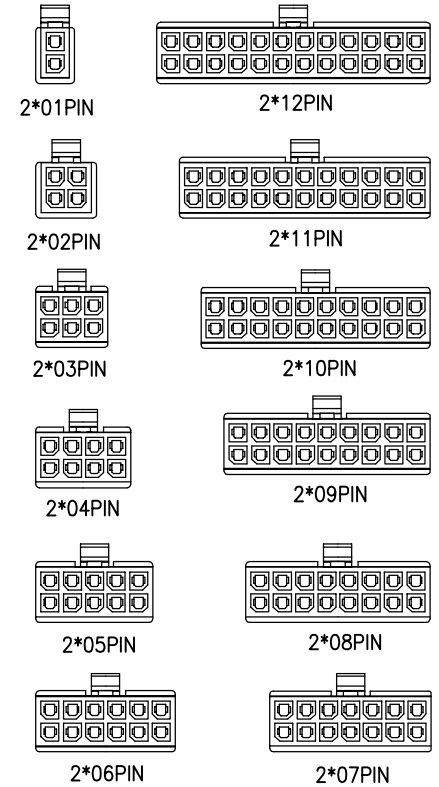
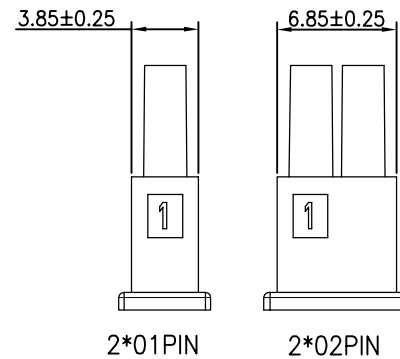
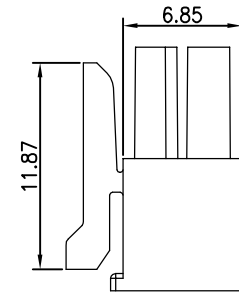
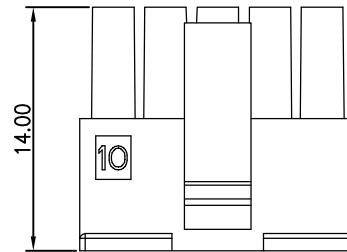
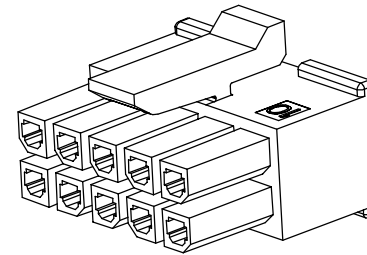
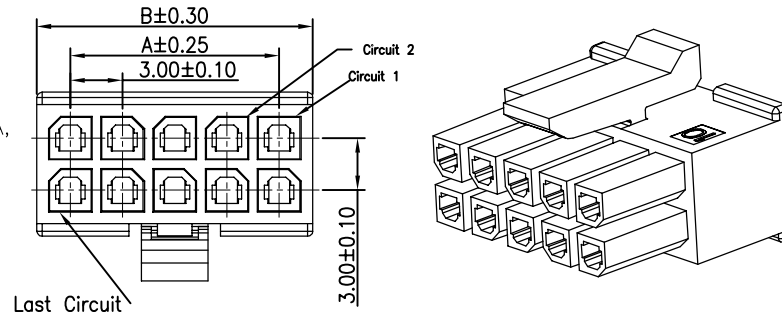
2. ELECTRICAL:

- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

63J2-H F Q XX B X

- H=Housing
- F=Female HSG
- 0=One row
- Pin 数码:
- 02=2PIN
- ~
- 12=12PIN
- I=WITHOUT EARS
- G=WITH EARS
- N=Natural
- B=Black



Poles	Dimensions(mm)		Poles	Dimensions(mm)	
	A	B		A	B
2*01			2*07	18.00	21.85
2*02	3.00		2*08	21.00	24.85
2*03	6.00	9.85	2*09	24.00	27.85
2*04	9.00	12.85	2*10	27.00	30.85
2*05	12.00	15.85	2*11	30.00	33.85
2*06	15.00	18.85	2*12	33.00	36.85

OPERATION		DRAW	WLY	2022.08.02	
X.X	±0.40	DESIGN	Jensen	2022.08.02	
X.XX	±0.25	CHECK	Jack	2022.08.02	
X.XXX	±0.15	APPROVE	Andy	2022.08.02	
Angle	±3°	UNIT	mm	SCALE	1:1
DIM.	TOL				

SOLEPIN 东莞市硕品电子有限公司
Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO		NEW		

SIZE	A4	PART NO.	63J3-HFOXXBX	
SHEET	1/1	TITLE:	WAFER 3.0MM Housing 双排	
PROJ.	☞	DRAW NO.	SP-712	

电镀图

NOTES:

1. FINISH:

- 1.1 HOUSING: NO-PA66, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

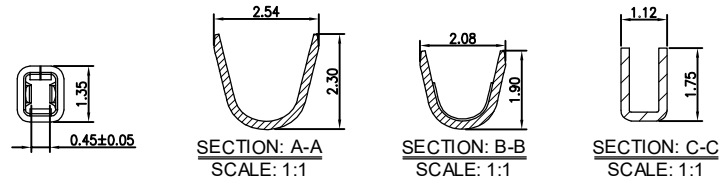
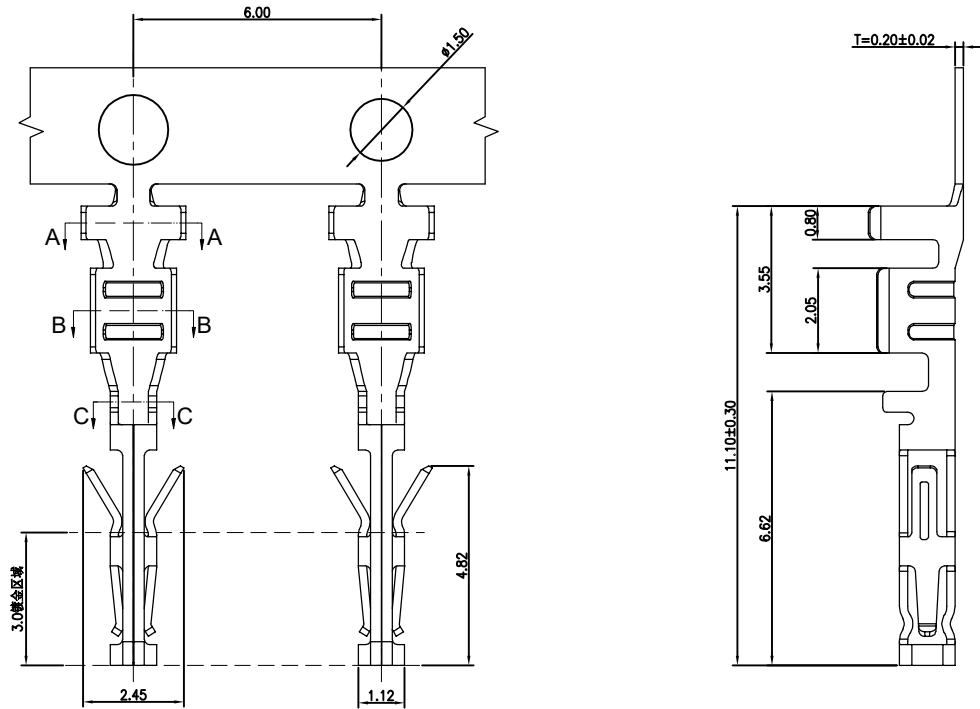
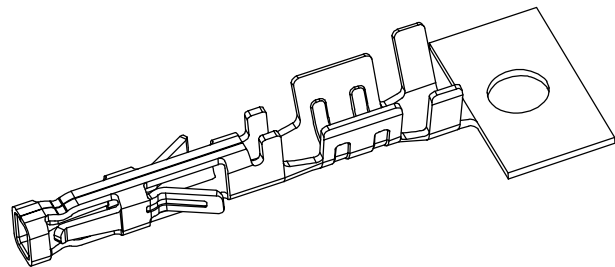
3. ORDER INFORMATION:

63J3-T F P XX B

T=Terminal
 F=Female Terminal
 P=Phosphor Bronze
 B=B-B Type

Plating code:

G6=Ni 20u"min; Contact Area 30u" Au
 G5=Ni 20u"min; Contact Area 15u" Au
 G0=Ni 50u"min; Contact Area Gold Flash
 SN=Ni 50u"min; Bright tin 100u" Min



					OPERATION	DRAW	WLY	2022.08.02	SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.					
					X.X ±0.40	DESIGN	Jensen	2022.08.02						
					X.XX ±0.25	CHECK	Jack	2022.08.02						
					X.XXX ±0.15	APPROVE	Andy	2022.08.02						
AO		NEW			Angle ±3°				SIZE	A4	PART NO.	63J3-TFPXXB		
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	SHEET	1/1	TITLE:	WAFER 3.0MM Housing双排
									PROJ.	☯	DRAW NO.	SP-715		

客户图

NOTES:

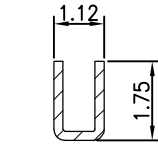
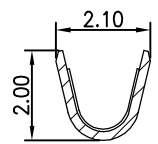
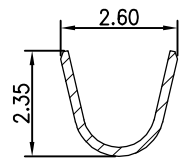
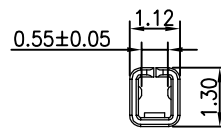
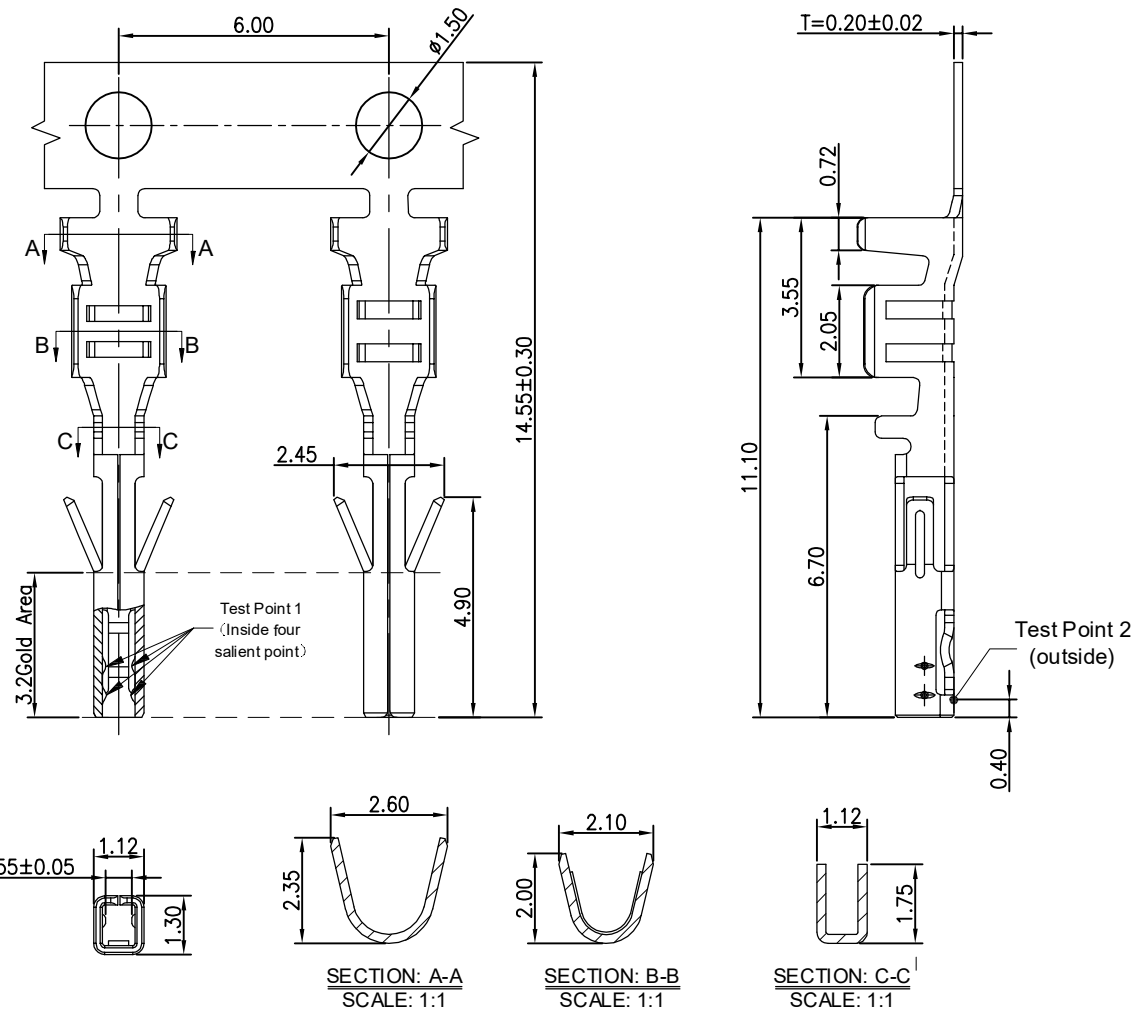
1. FINISH:
 - 1.1 HOUSING: NO-PA66, UL94V-0.
 - 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
 - 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
 - 2.1 CURRENT RATING: 5A Max AC/DC;
 - 2.2 VOLTAGE RATING: 250V AC/DC.
 - 2.3 CONTACT RESISTANCE: 120mΩ MAX.
 - 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
 - 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.
3. ORDER INFORMATION:

63J3-T F P XX V

T=Terminal
 F=Female Terminal
 P=Phosphor Bronze
 V=Convex hull limit

Plating code:

- G6=Contact point gold 30u"(inside test piont1)
 Gold area1u"(outside test piont2)
 Other area Ni30u" min
- G5=Contact point gold 15u"(inside test piont1)
 Gold area1u"(outside test piont2)
 Other area Ni30u" min
- G0=Contact Area Gold Flash(outside test piont2)
- SN=Bright tin platin(outside test piont 2)



SECTION: A-A
SCALE: 1:1

SECTION: B-B
SCALE: 1:1

SECTION: C-C
SCALE: 1:1

					OPERATION	DRAW	WLY	2022.08.02	SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.					
					X.X ±0.40	DESIGN	Jensen	2022.08.02						
					X.XX ±0.25	CHECK	Jack	2022.08.02						
					X.XXX ±0.15	APPROVE	Andy	2022.08.02						
AO		NEW			Angle ±3°				SIZE	A4	PART NO.	63J3-TFPXXV		
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	SHEET	1/1	TITLE:	WAFER 3.0MM Housing双排
									PROJ.	SP-714	PROJ.	SP-714	PROJ.	SP-714

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: NO-PA66, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

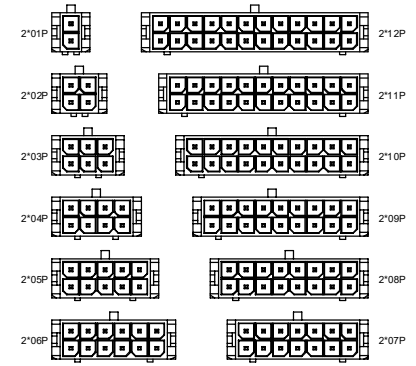
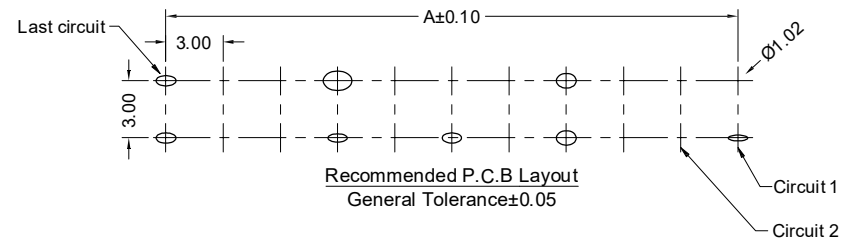
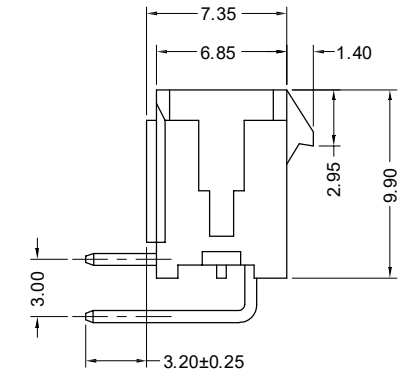
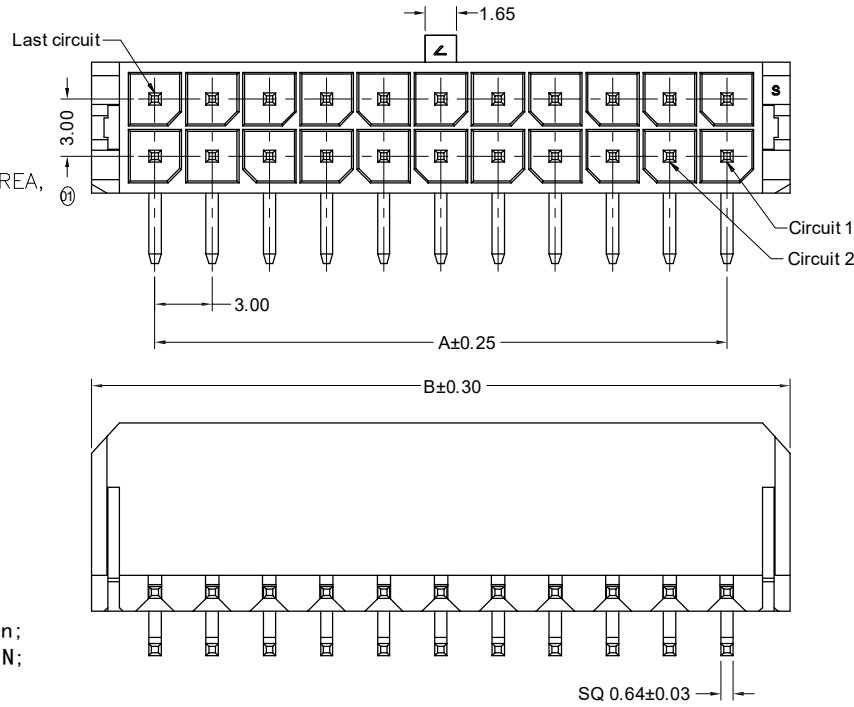
- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

63J3-W D R D-XX XX B X

W=Wafer
D=Double row
R=Right Angle 90°
D=DIP
Pin 数码:
02=2*01PIN
~
24=2*12PIN

T=TRAY
R=REEL
B=BLACK
S6=Contact Area Au 30u" Min;
Solder Area SN 100u" MIN;
Ni50u" Min
G0=GOLD FLASH
G3=GOLD 4u"
SW=MATTE TIN
SN=BRIGHT TIN



Scale 1:3

Poles	Dimensions (mm)	
	A	B
2*01	---	6.65
2*02	3.00	9.65
2*03	6.00	12.65
2*04	9.00	15.65
2*05	12.00	18.65
2*06	15.00	21.65
2*07	18.00	24.65
2*08	21.00	27.65
2*09	24.00	30.65
2*10	27.00	33.65
2*11	30.00	36.65
2*12	33.00	39.65

					OPERATION	DRAW	WLY	2022.08.02	SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.				
					X.X ±0.40	DESIGN	Jensen	2022.08.02					
					X.XX ±0.25	CHECK	Jack	2022.08.02					
					X.XXX ±0.15	APPROVE	Andy	2022.08.02					
AO		NEW			Angle ±3°				SIZE	A4	PART NO.	63J3-WDRD-XXXXBX	
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM. TOL	UNIT	mm	SCALE	1:1	SHEET	1/1	TITLE:	WAFER 3.0MM
										PROJ.	☞	DRAW NO.	SP-718

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: NO-PA66, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

63J3-W D R D-XX XX B X A

W=Wafer
D=Double row
R=Right Angle 90°
D=DIP

A=WITH POSITIONING COLUMN
T=TRAY
R=REEL
B=BLACK

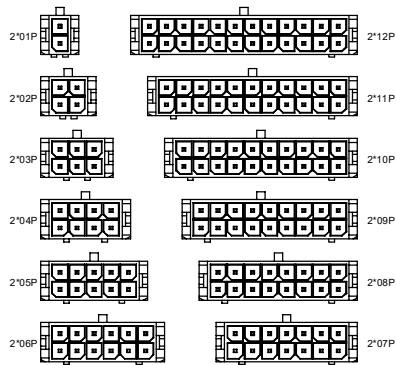
Pin 数码:
02=2*01PIN
~
24=2*12PIN

S6=Contact Area Au 30u" Min;
Solder Area SN 100u" Min;
Ni 50u" Min

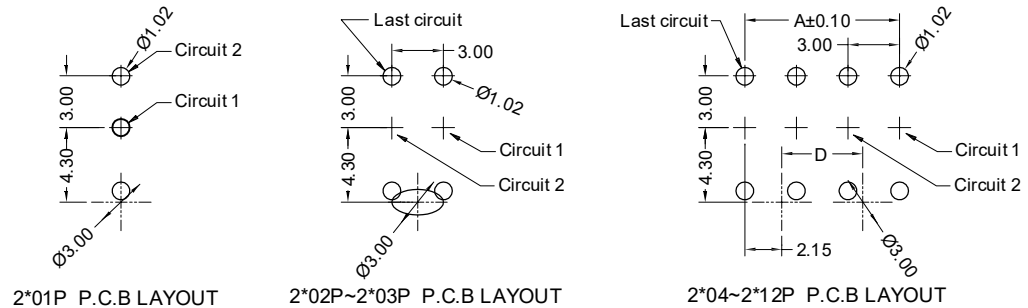
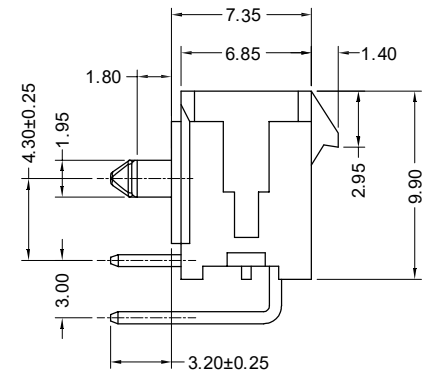
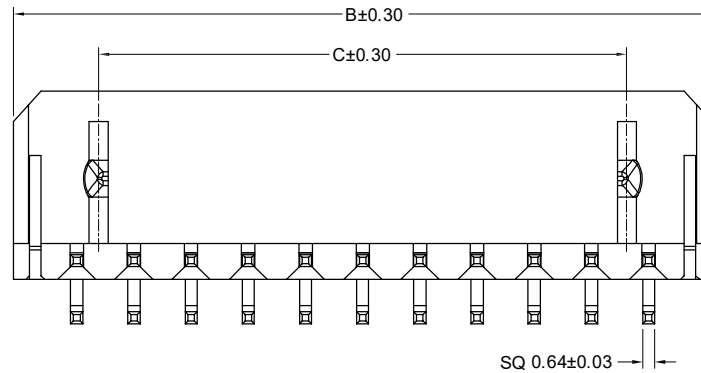
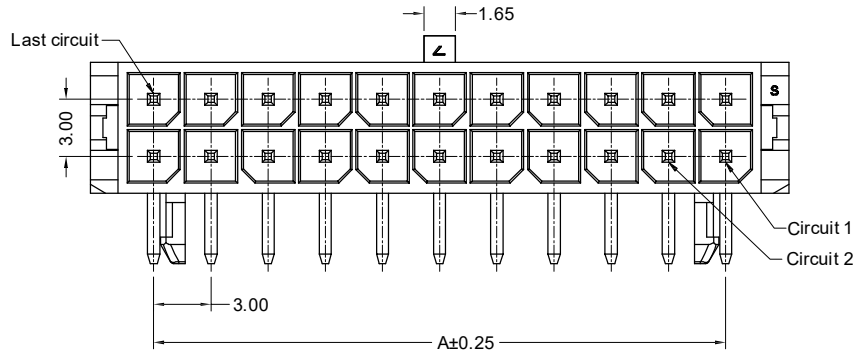
G0=GOLD FLASH
G3=GOLD 4u"

SW=MATTE TIN
SN=BRIGHT TIN

Poles	Dimensions (mm)			
	A	B	C	D
2*01	---	6.65	2.00	---
2*02	3.00	9.65	2.00	---
2*03	6.00	12.65	2.00	---
2*04	9.00	15.65	6.70	4.70
2*05	12.00	18.65	9.70	7.70
2*06	15.00	21.65	12.70	10.70
2*07	18.00	24.65	15.70	13.70
2*08	21.00	27.65	18.70	16.70
2*09	24.00	30.65	21.70	19.70
2*10	27.00	33.65	24.70	22.70
2*11	30.00	36.65	27.70	25.70
2*12	33.00	39.65	30.70	28.70



Scale 1:3



OPERATION		DRAW	WLY	2022.08.02
X.X	±0.40	DESIGN	Jensen	2022.08.02
X.XX	±0.25	CHECK	Jack	2022.08.02
X.XXX	±0.15	APPROVE	Andy	2022.08.02
Angle	±3°	UNIT	mm	SCALE 1:1
DIM.	TOL	PROJ.	SCALE	1:1

SOLEPIN 东莞市硕品电子有限公司
Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO		NEW		

SIZE	A4	PART NO.	63J3-WDRD-XXXXBXA
SHEET	1/1	TITLE:	WAFER 3.0MM Housing 双排
PROJ.	SP-719	DRAW NO.	

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: NO-PA66, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

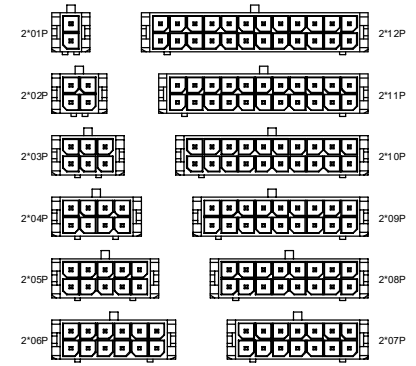
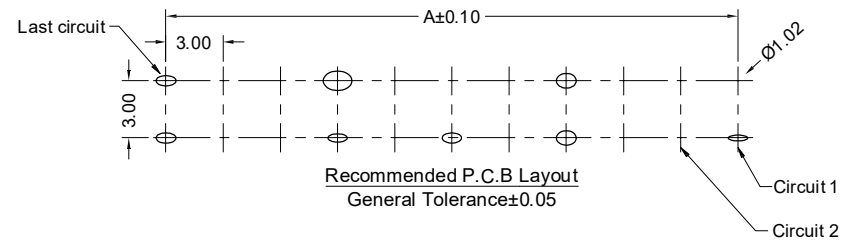
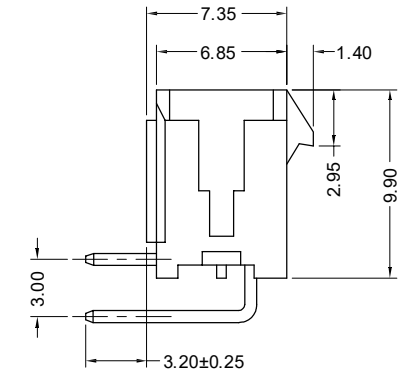
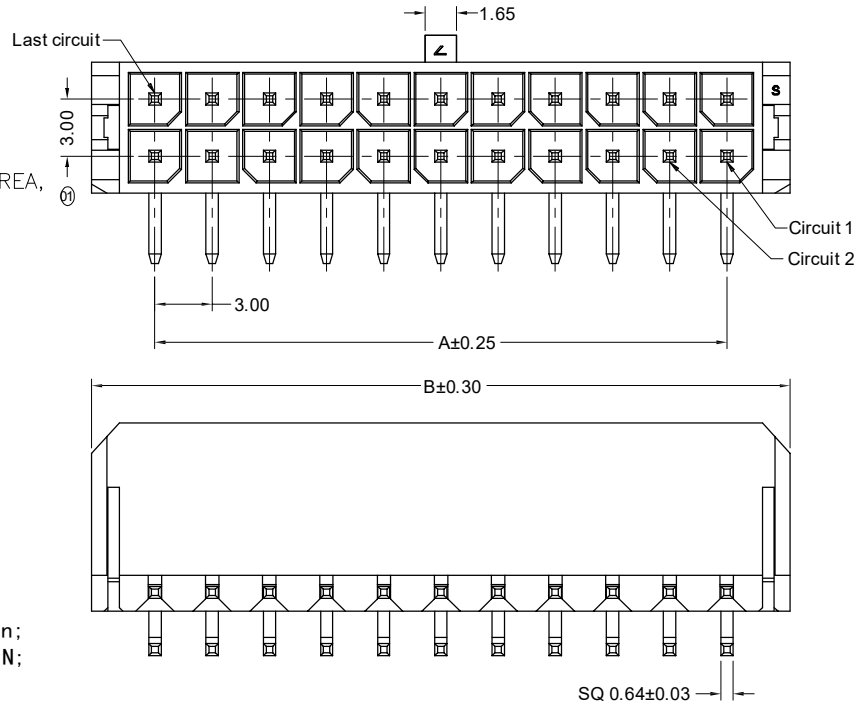
- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

63J2-W D R D-XX XX B X

W=Wafer
D=Double row
R=Right Angle 90°
D=DIP
Pin 数码:
02=2*01PIN
~
24=2*12PIN

T=TRAY
R=REEL
B=BLACK
S6=Contact Area Au 30u" Min;
Solder Area SN 100u" MIN;
Ni 50u" Min
G0=GOLD FLASH
G3=GOLD 4u"
SW=MATTE TIN
SN=BRIGHT TIN



Scale 1:3

Poles	Dimensions (mm)	
	A	B
2*01	---	6.65
2*02	3.00	9.65
2*03	6.00	12.65
2*04	9.00	15.65
2*05	12.00	18.65
2*06	15.00	21.65
2*07	18.00	24.65
2*08	21.00	27.65
2*09	24.00	30.65
2*10	27.00	33.65
2*11	30.00	36.65
2*12	33.00	39.65

					OPERATION	DRAW	WLY	2022.08.02	SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.				
					X.X ±0.40	DESIGN	Jensen	2022.08.02					
					X.XX ±0.25	CHECK	Jack	2022.08.02					
					X.XXX ±0.15	APPROVE	Andy	2022.08.02					
AO		NEW			Angle ±3°				SIZE	A4	PART NO.	63J3-WDRD-XXXXBX	
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM. TOL	UNIT	mm	SCALE	1:1	SHEET	1/1	TITLE:	WAFER 3.0MM
										PROJ.	☞	DRAW NO.	SP-718

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: NO-PA66, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 5A Max AC/DC;
- 2.2 VOLTAGE RATING: 250V AC/DC.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

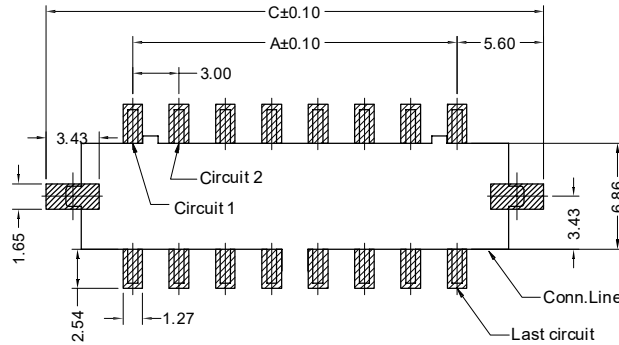
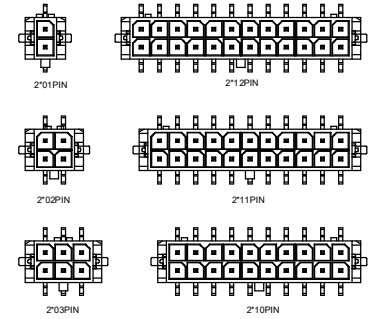
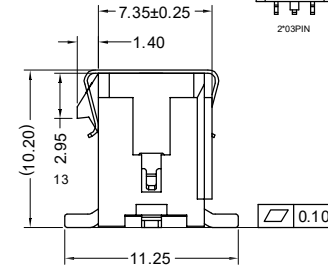
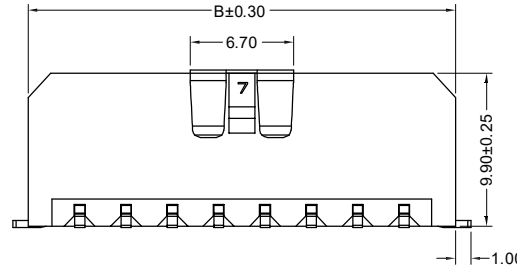
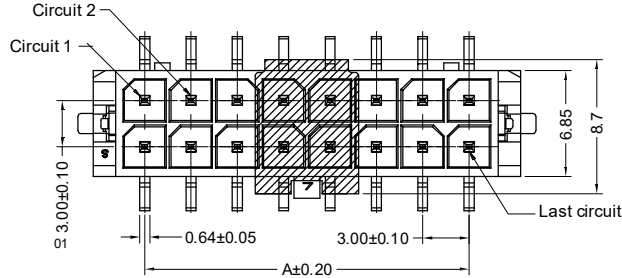
63J3-W D V S-XX XX B X D

W=Wafer
 D=Double row
 V=Vertical 180°
 S=SMT
 D=The Solder tab
 T=Tray
 R=Reel
 B=Black

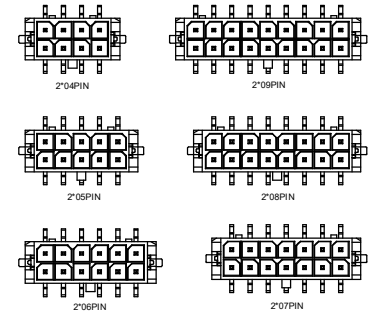
Pin 数码:
 02=2*01PIN
 ~
 24=2*12PIN

SW=Ni 50u" Min;
 Matte Tin 100u" Min;
 G6=Contact Area Au 30u" Min;
 Wolder Area Ni 50u" Min;
 Matte Tin 100u" Min
 G5=Contact Area Au 15u" Min;
 Wolder Area Ni 50u" Min;
 Matte Tin 100u" Min

Poles	Dimensions(mm)		
	A	B	C
2*01	---	6.65	11.20
2*02	3.00	9.65	14.20
2*03	6.00	12.65	17.20
2*04	9.00	15.65	20.20
2*05	12.00	18.65	23.20
2*06	15.00	21.65	26.20
2*07	18.00	24.65	29.20
2*08	21.00	27.65	32.20
2*09	24.00	30.65	35.20
2*10	27.00	33.65	38.20
2*11	30.00	36.65	41.20
2*12	33.00	39.65	44.20



Recommended P.C.B Layout
 General Tolerance±0.05



OPERATION		DRAW	WLY	2022.08.02
X.X	±0.40	DESIGN	Jensen	2022.08.02
X.XX	±0.25	CHECK	Jack	2022.08.02
X.XXX	±0.15	APPROVE	Andy	2022.08.02
Angle	±3°	UNIT	mm	SCALE 1:1
DIM.	TOL	UNIT	mm	SCALE 1:1

SOLEPIN 东莞市硕品电子有限公司
 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO		NEW		

SIZE	A4	PART NO.	63J3-WDVS-XXXXBXD
SHEET	1/1	TITLE:	WAFER 3.0MM Housing双排
PROJ.	SP-720	DRAW NO.	

客户图

NOTES:

1. FINISH:

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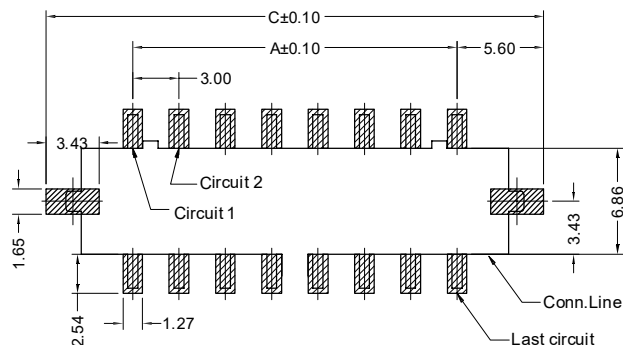
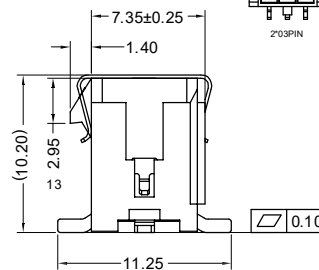
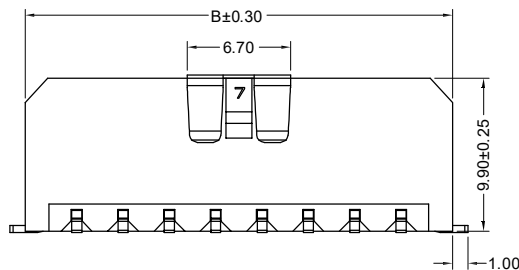
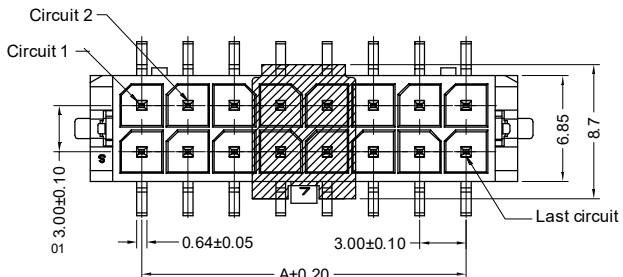
63J2-W D V S-XX XX B X D

W=Wafer
 D=Double row
 V=Vertical 180°
 S=SMT
 D=The Solder tab
 T=Tray
 R=Reel
 B=Black

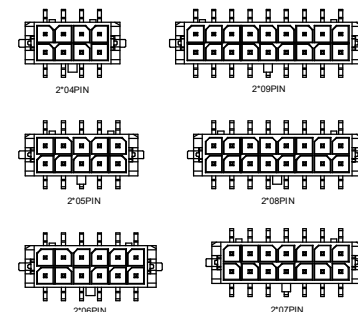
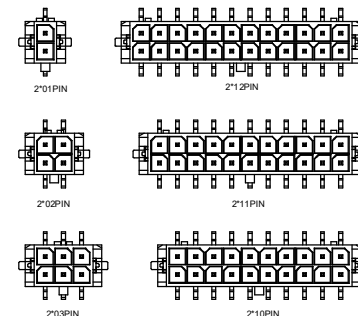
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 General Tolerance±0.05



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 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO		NEW		

SIZE	A4	PART NO.	63JS-WDVS-XXXXBXD
SHEET	1/1	TITLE:	WAFER 3.0MM Housing双排
PROJ.	☯	DRAW NO.	SP-720